

Title (en)

METHOD FOR PRODUCING A SEMICONDUCTOR COMPONENT CONTROLLED BY FIELD EFFECT

Title (de)

HERSTELLUNGSVERFAHREN FÜR EIN DURCH FELDEFFEKT GESTEUERTES HALBLEITERBAUELEMENT

Title (fr)

PROCEDE POUR LA FABRICATION D'UN COMPOSANT A SEMI-CONDUCTEURS COMMANDE PAR EFFET DE CHAMP

Publication

**EP 0998754 A1 20000510 (DE)**

Application

**EP 98947305 A 19980717**

Priority

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Abstract (en)

[origin: DE19731496A1] The invention relates to a method for producing semiconductor components controlled by field effect e.g. but not exclusively MIS power transistors, wherein said semiconductor components comprise a substrate of a first capacity type, covered by a gate insulating layer. The inventive method for producing semiconductor components controlled by field effect and comprising a semiconductor substrate(1) of a first capacity type and a gate insulating layer(2) on the surface(3) of said substrate (1) consists inter alia in making a second capacity type trough(4) in the semiconductor substrate (1) by implanting first impurities and is characterized by steps undertaken to produce a semiconductor layer (8,9) of a first given thickness on the gate insulating layer (2) before producing the trough (4) and reducing the semiconductor layer (8,9) in a given area to obtain a residual layer (6) of a second given thickness, so that the semiconductor layer (9) acts as an implantation barrier outside the given area when the trough (4) is produced.

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**H01L 21/336; H01L 29/78**

IPC 8 full level

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